

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
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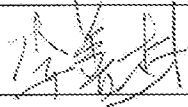
EPAS ID: PAT3304160

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
SUN-JAE LEE	03/30/2015
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<b>State/Country:</b>	KOREA, REPUBLIC OF
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	14682470
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<b>NAME OF SUBMITTER:</b>	ALICIA M. CHOI
<b>SIGNATURE:</b>	/Alicia M. Choi/
<b>DATE SIGNED:</b>	04/09/2015
<b>Total Attachments: 2</b>	
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source=NewApp_0120521224_AssignmentExecuted#page2.tif	



This Assignment includes the above-identified application, any and all United States and foreign patents, utility models, and design registrations granted for any of the inventions and improvements that are the subject of the above-identified application, and the right to claim priority based on the filing date of the above-identified application under the International Convention for the Protection of Industrial Property, the Patent Cooperation Treaty, the European Patent Convention, and all other treaties of like purposes; and I authorize the Assignee to apply in all countries in my name or in its own name for patents, utility models, design registrations, like rights of exclusion, and inventors' certificates for any of the inventions and improvements that are the subject of the above-identified application; and I agree for myself and my heirs, legal representatives, and assigns without further compensation to perform such lawful acts and to sign such further applications, Assignments, preliminary statements, and other lawful documents as the Assignee may reasonably request to effectuate fully this Assignment.

In witness whereof, I, as a below-named inventor and assignor, intending to be legally bound, have hereunto affixed my signature on the date indicated below next to my signature.

Inventor's Legal Name	Sun-Jae LEE		
Inventor's Signature		Date	20 MAR. 2015
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